

IN THE CLAIMS

Please amend claim 21 as follows:

21. (Amended) A semiconductor device comprising:

a semiconductor chip;

a bump disposed on a surface of the semiconductor chip;

a protective member disposed on the surface of the semiconductor chip, the protective member having an opening portion from which the bump is exposed; and

a movable portion disposed on a region that is covered by the protective member.

Please add the following new claims:

39. (New) The semiconductor device according to claim 31, wherein the first plane surface on which the pad portion is formed is different than the opening portion in which the movable portion is disposed.

40. (New) The semiconductor device according to claim 21, wherein the bump is further disposed on another region different than the region of the movable portion.